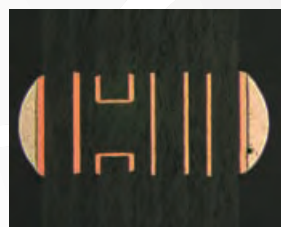
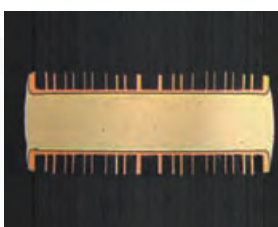
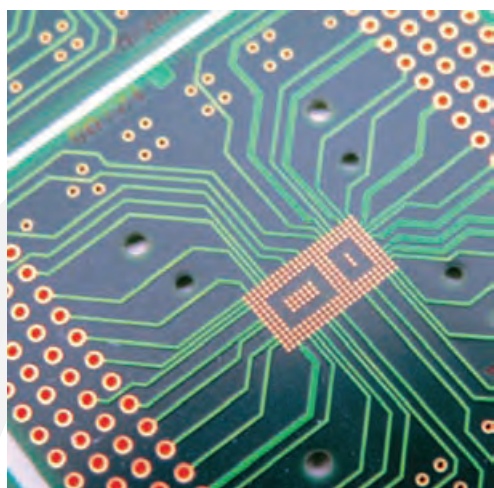


ALWAYS CLOSE TO YOUR NEEDS!



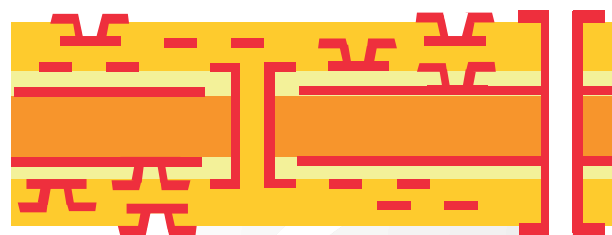
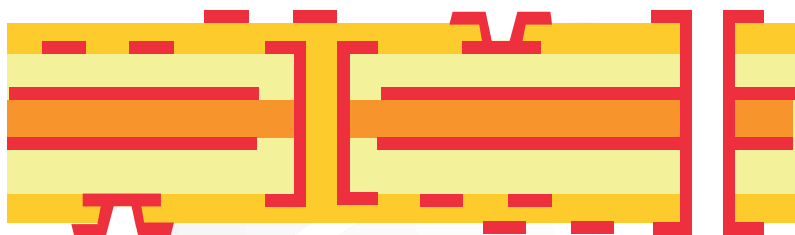
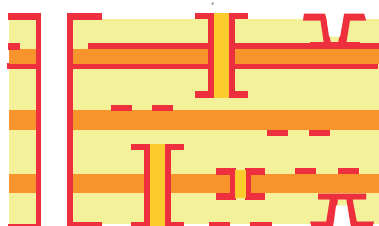
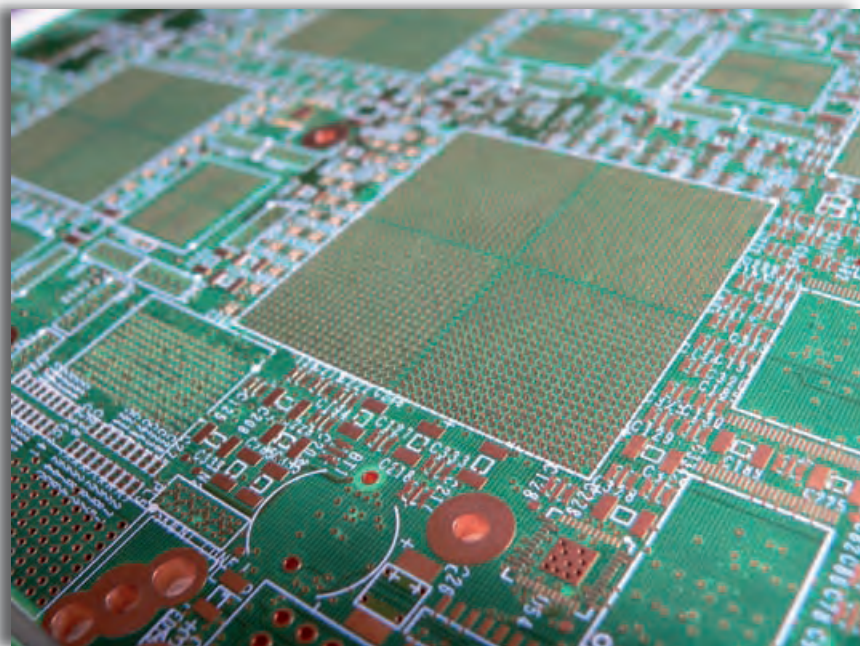
SBU PCBs



SBU PCBs

Production plants:
Elco Italy, Elco France

Description:
A technological solution for
High-Density PCB.



Technical

Construction

Up to 32 Layers
Sequential multilayers
Base copper thickness :
5 μ , 9 μ , 12 μ , 18 μ , 35 μ , 70 μ , 105 μ

Dimensions

Maximum PCB size : 478 x 592 mm
Maximum thickness : 5 mm

Base material

- High Tg epoxy (Tg>175°C) compatible RoHS
- Materials for high frequencies (4 to 15 Ghz)
- Polyimide
- ROGER 4350
- Green material (halogen free)

Surfaces finishing

- Electroless Nickel/Gold (ENIG)
- Electroplated Nickel/Gold
- Immersion tin
- Tin Lead reflow
- OSP

Line & Spacing

External standard : 60 μ /75 μ
Internal standard : 50 μ /75 μ
Internal advanced : 40 μ /60 μ

Blind vias (mechanical)

Drilling diameter : 100 μ

Thru hole

Min drilling diameter : 150 μ
Aspect ratio : 16:1

Laser vias

- Sequential multilayers (3 levels)
- Stacked microvias
- Via copper filling
- Drilling diameter : 75 μ

BGA

- Up to 1980 I/O
- Pitch : 1, 0.8, 0.65, 0.5, 0.4, 0.3 mm

Flip Chip

< 250 μ pitch

Impedance Check

- Tolerance of impedance: \pm 10%
- Reflectometer Polar

Tests

- 100% Automatic-Optical-Inspection
- 100% electrical test
- Visual inspection

Quality Controls

- Guarantee of custom-designed quality standards and production according to international guidelines:
 - Vision 2000 - CNES - AS9100B
 - EN9100:2003/S1 - JISQ9100:2004
 - UL Certified: 94V-0 up to 130°
- Process including reliability tests (daisy chain board)
- State of the art Laboratory